



## THERMOPLASTIC POLYESTER RESIN

Rynite\$ 550HTE BK503 is a 50% glass reinforced modified polyethylene terephthalate resin with excellent high temperature dielectric properties

Product information			
Resin Identification	PET-GF50		ISO 1043
Part Marking Code	>PET-GF50<		ISO 11469
Dhaqlagical properties			
Rheological properties			
Melt volume-flow rate		cm <sup>3</sup> /10min	ISO 1133
Temperature	280		
Load		kg	100 007 4000
Viscosity number		cm³/g	ISO 307, 1628
Moulding shrinkage, parallel	0.2		ISO 294-4, 2577
Moulding shrinkage, normal	0.7	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	18000	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min		MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	1.8		ISO 527-1/-2
Flexural modulus	16000		ISO 178
Flexural strength		MPa	ISO 178
Charpy impact strength, 23°C	65	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	11	kJ/m²	ISO 179/1eA
Poisson's ratio	0.33		
Thermal properties			
Melting temperature, 10°C/min	251	°C	ISO 11357-1/-3
Glass transition temperature, 10°C/min		°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	235		ISO 75-1/-2
Coefficient of linear thermal expansion		E-6/K	ISO 11359-1/-2
(CLTE), parallel	.0	2 0/11	100 11000 17 2
Coefficient of linear thermal expansion (CLTE),	81	E-6/K	ISO 11359-1/-2
normal			
Electrical properties			
Electric strength	30	kV/mm	IEC 60243-1
Physical/Other properties			
	1750	Le en / 100 3	100 1100
Density  Density of realt		kg/m <sup>3</sup>	ISO 1183
Density of melt	1560	kg/m³	

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#### Injection

Drying Recommended	yes
Drying Temperature	120 °C
Drying Time, Dehumidified Dryer	4-6 h
Processing Moisture Content	≤0.01 <sup>[1]</sup> %
Melt Temperature Optimum	285 °C
Min. melt temperature	280 °C
Max. melt temperature	300 °C
Mold Temperature Optimum	130 °C
Min. mould temperature	120 °C
Max. mould temperature	140 <sup>[2]</sup> °C
Ejection temperature	201 °C

[1]: At levels above 0.01%, strength and toughness will decrease, even though parts may not exhibit surface defects.

#### Characteristics

Processing Injection Moulding

#### Additional information

Injection molding

When lower mold temperatures are used, the initial warpage and shrinkage will be lower, but the surface appearance will be poorer and the dimensional change may be greater when parts are subsequently heated.

Higher temperature settings for the rear of the barrel will minimize glass fiber attrition, though overall barrel residence time should be considered.

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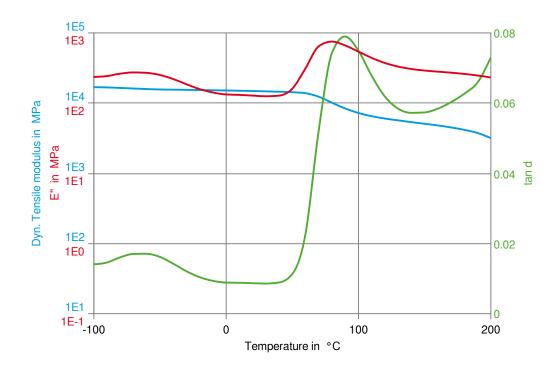
<sup>[2]: (6</sup>mm - 1mm thickness)





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Dynamic Tensile modulus-temperature



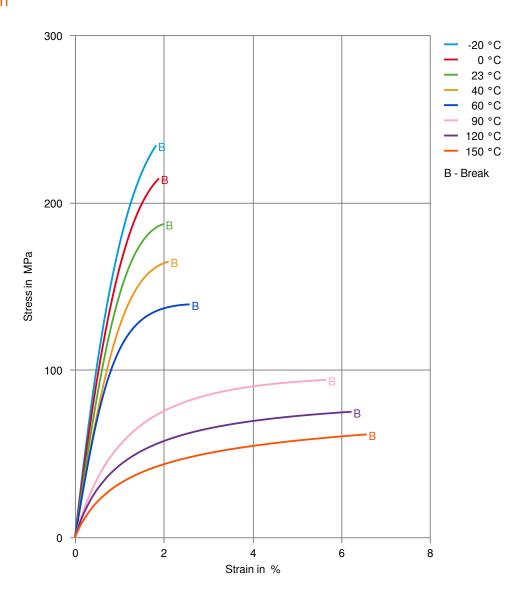
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## THERMOPLASTIC POLYESTER RESIN

### Stress-strain



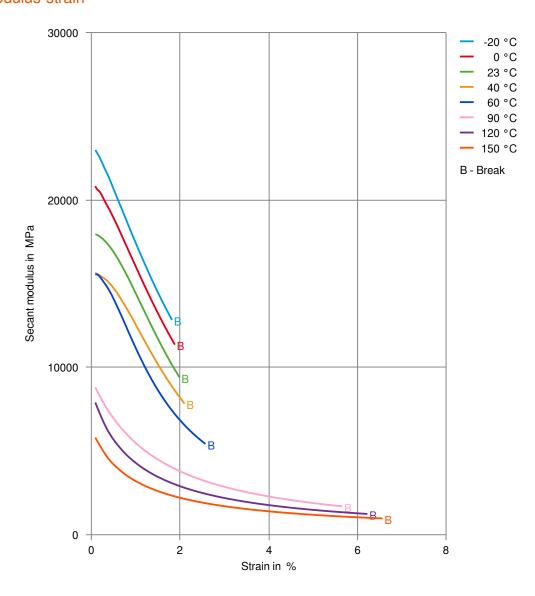
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## THERMOPLASTIC POLYESTER RESIN

### Secant modulus-strain



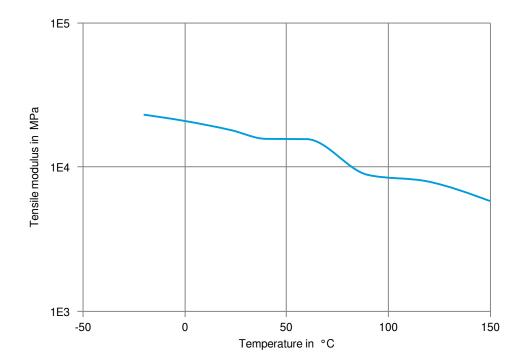
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## THERMOPLASTIC POLYESTER RESIN

Tensile modulus-temperature



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Revised: 2025-04-22 Source: Celanese Materials Database

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